

Tin Whisker Growth Experiment

1. Sample: DO-204 (Matte tin) 10 Pcs
 SMA (Matte tin) 10 Pcs
 TO-220 (Bright tin) 10 Pcs
 RS4M (Bright tin) 10 Pcs

2. Plating thickness: Typ. 5um

3. Post baking after plating: 150°C for 1 Hr.

4. Environment condition (Humidity): 85°C / 85%RH

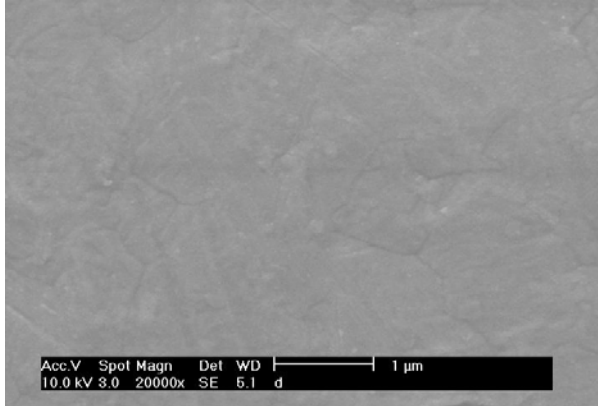
5. Microscope:



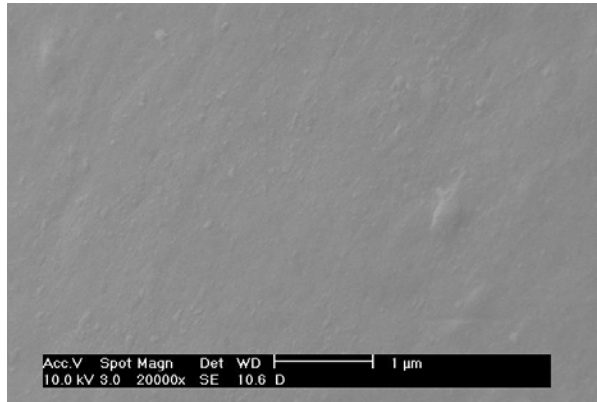
4-1 Post 500Hrs results under a 20000X microscope

PREPARED	DATE	APPROVED	DATE
J H Wang	Mar 15, 2006	Richard	Mar 15, 2006

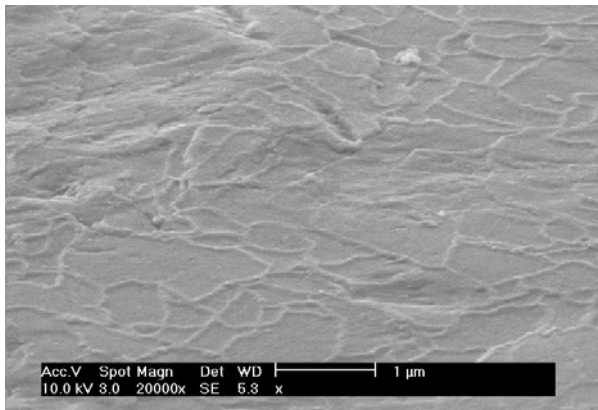
DO204



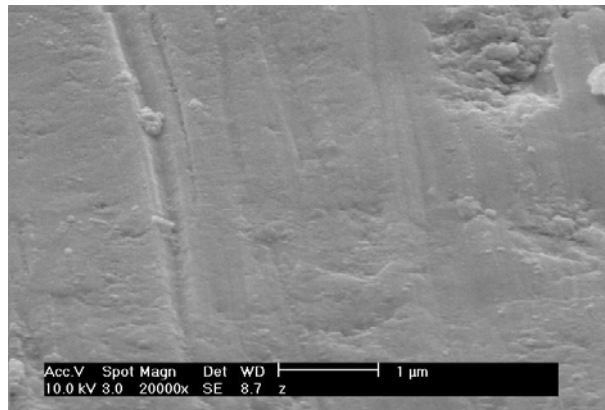
SMA



TO220



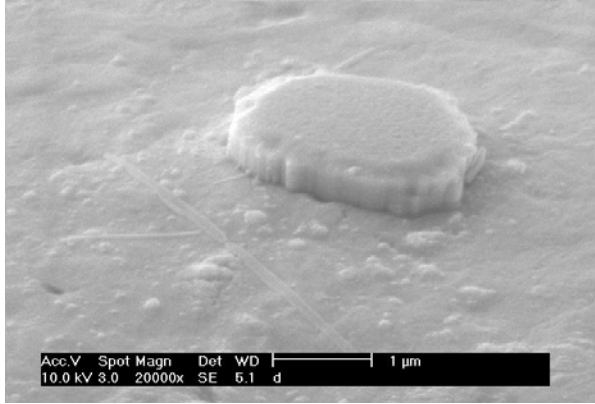
RS4M



4-2 Post 1000Hrs results under a 20000X microscope

PREPARED	DATE	APPROVED	DATE
J H Wang	Mar 15, 2006	Richard	Mar 15, 2006

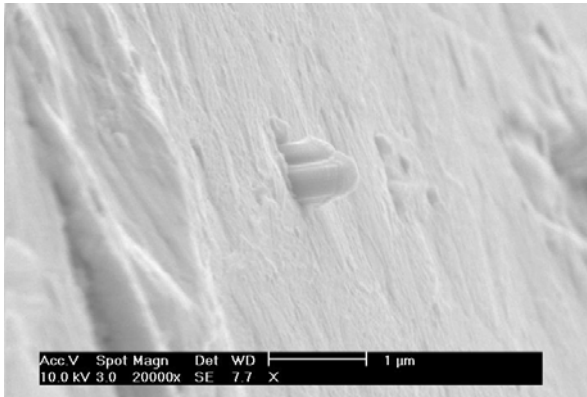
DO-204



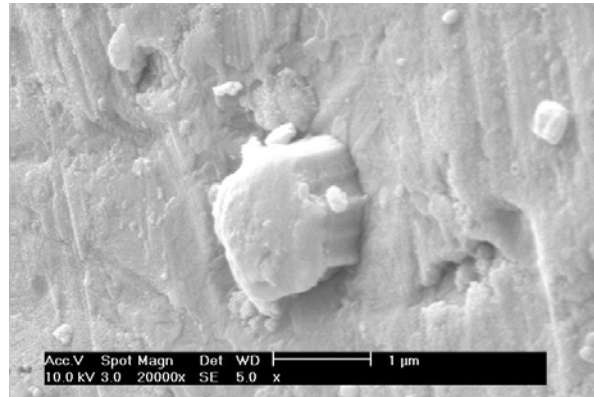
SMA



TO220



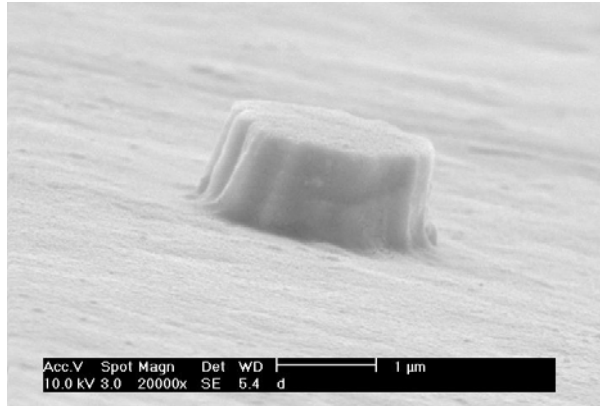
RS4M



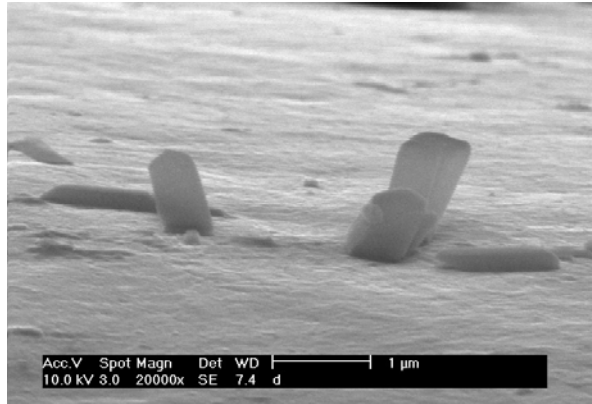
4-3 Post 2000Hrs under a 20000X microscope

PREPARED	DATE	APPROVED	DATE
J H Wang	Mar 15, 2006	Richard	Mar 15, 2006

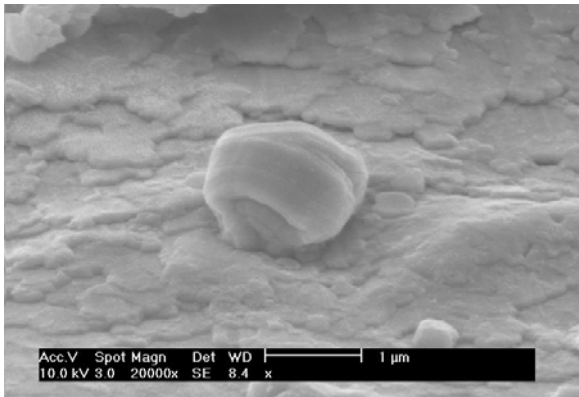
DO204



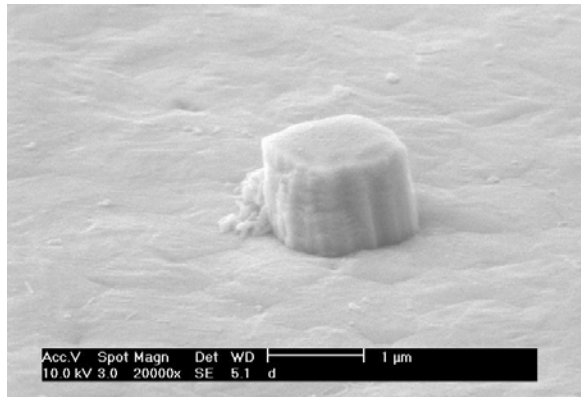
SMA



TO220



RS4M



4-4 Post 3000Hrs under a 20000X microscope

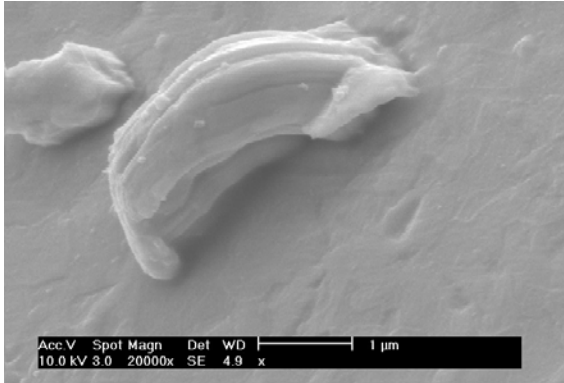
PREPARED
J H Wang

DATE
Mar 15, 2006

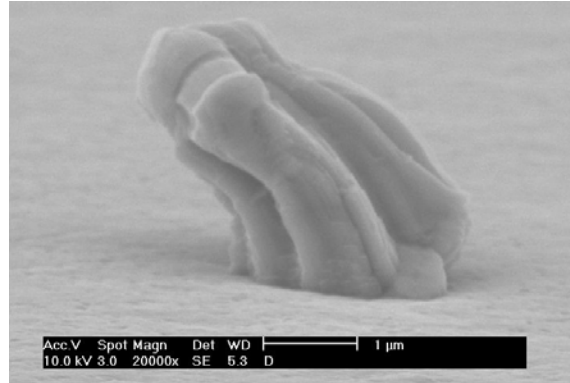
APPROVED
Richard

DATE
Mar 15, 2006

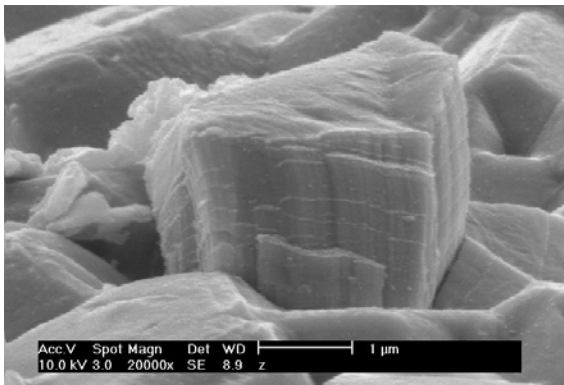
DO204



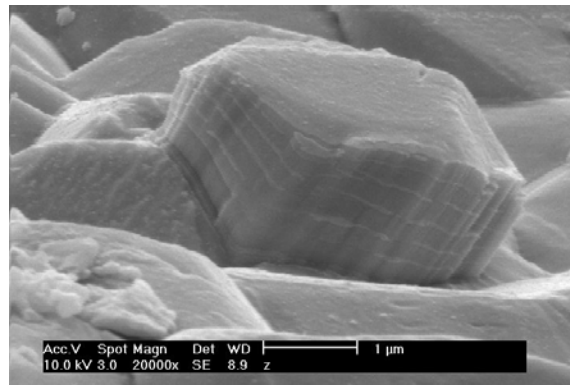
SMA



TO220



RS4M



5. Conclusion:

PREPARED J H Wang	DATE Mar 15, 2006	APPROVED Richard	DATE Mar 15, 2006
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The post observation confirmed that after Humidity condition of **85°C / 85%RH for 3000 Hrs**, our Tin-plating process with 100% post bake of 150°C for 1 hour reduces the promotion of major whisker growth per JESD22A121 specifications. All test samples observed under a 20000X microscope displayed end results of Tin-whisker growth up to 4- 5um maximum with a total numbers of whisker less than 2 in 1mm x 1mm area.

PREPARED	DATE	APPROVED	DATE
J H Wang	Mar 15, 2006	Richard	Mar 15, 2006